## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Application Number : 10/553,470 Confirmation No.: 8935

National Phase of International App'l. No. PCT/DE2004/000801

Applicant Ralf LERNER

Filed : May 19, 2006

Title : MONITORING THE REDUCTION OF THICKNESS AS

MATERIAL IS REMOVED FROM A WAFER COMPOSITE AND

TEST STRUCTURE FOR MONITORING REMOVAL OF

**MATERIAL** 

TC/Art Unit : 2818

Examiner: : Lopez Esquerra, Andres

Docket No. : 60291.000041

Customer No. : **21967** 

## MAIL STOP AMENDMENTS

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

## RESPONSE TO FINAL OFFICE ACTION UNDER 37 C.F.R. § 1.116

Sir:

## **AMENDMENT**

Amendments to the Claims appear in the Listing of Claims beginning on page 2 of this paper.

Remarks appear on page 7 of this paper.